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(54) LAMINATED COMPOSITE

(57)Abstract:

PURPOSE: To obtain a laminated composite wherein constituents are bonded excellently to each other, by coating a base sheet with a film comprising at least one layer of which the base is polyamide obtained from a polycondensate of an aliphatic α,ω -dicarboxylic acid and xylylenediamine.

CONSTITUTION: A laminated composite comprises a film (A) bonded to a base sheet by lamination. The film (A) comprises at least one layer of which the base is polyamide (P) obtained by polycondensation of an aliphatic α,ω -dicarboxylic acid and xylylenediamine. When this polyamide is selected as a barrier polymer, the film (A) and a constituent at a processing temperature of 250-320°C are bonded excellently to each other. Besides, the film (A) comprises also at least one layer (C) of which the base is modified polyolefin. This material can be coextruded with the polyamide (P) at a high temperature and improves the moisture resistance of the polyamide (P) so that absorption of water be avoided, while it enhances adhesion among the base sheet, the polyamide (P) and other layers of the film (A).

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